



TAI-SAW TECHNOLOGY CO., LTD.

No. 3, Industrial 2nd Rd., Ping-Chen Industrial District,
Taoyuan, 324, Taiwan, R.O.C.

TEL: 886-3-4690038 FAX: 886-3-4697532

E-mail: tstsales@mail.taisaw.com Web: www.taisaw.com

Product Specifications Approval Sheet

Product Description: DR Filter 5710MHz (BW=445MHz) 8.6x3.45x3.0

TST Parts No.: TR0013A

Customer Parts No.: _____

Company: _____
Division: _____
Approved by : _____
Date: _____

Checked by: _____ Hong Pu Lin *Hong Pu Lin*

Approval by: _____ Andy Yu *Andy Yu*

Date: _____ 06 / 20 / 2018

1. Customer signed back is required before TST can proceed with sample build and receive orders.
2. Orders received without customer signed back will be regarded as agreement on the specifications.
3. Any specifications changes must be approved upon by both parties and a new revision of specifications shall be released to reflect the changes.



TAI-SAW TECHNOLOGY CO., LTD.

No.3, Industrial 2nd Rd., Ping-Chen Industrial District, Taoyuan, Taiwan, R.O.C.

TEL: 886-3-4690038 FAX: 886-3-4697532

E-mail: tstsales3@mail.taisaw.com Web: www.taisaw.com

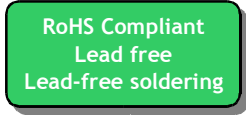
DR Filter 5710MHz 445MHz BW

MODEL NO.: TR0013A

REV. NO.1

A. MAXIMUM RATING:

1. Operating temperature range: -40°C to 85°C
2. Storage temperature range: -40°C to 85°C
3. Input Power Level : 1W
4. Input/Output Impedance:50 Ohm
5. Moisture Sensitivity Level: Level(**MSL1**)

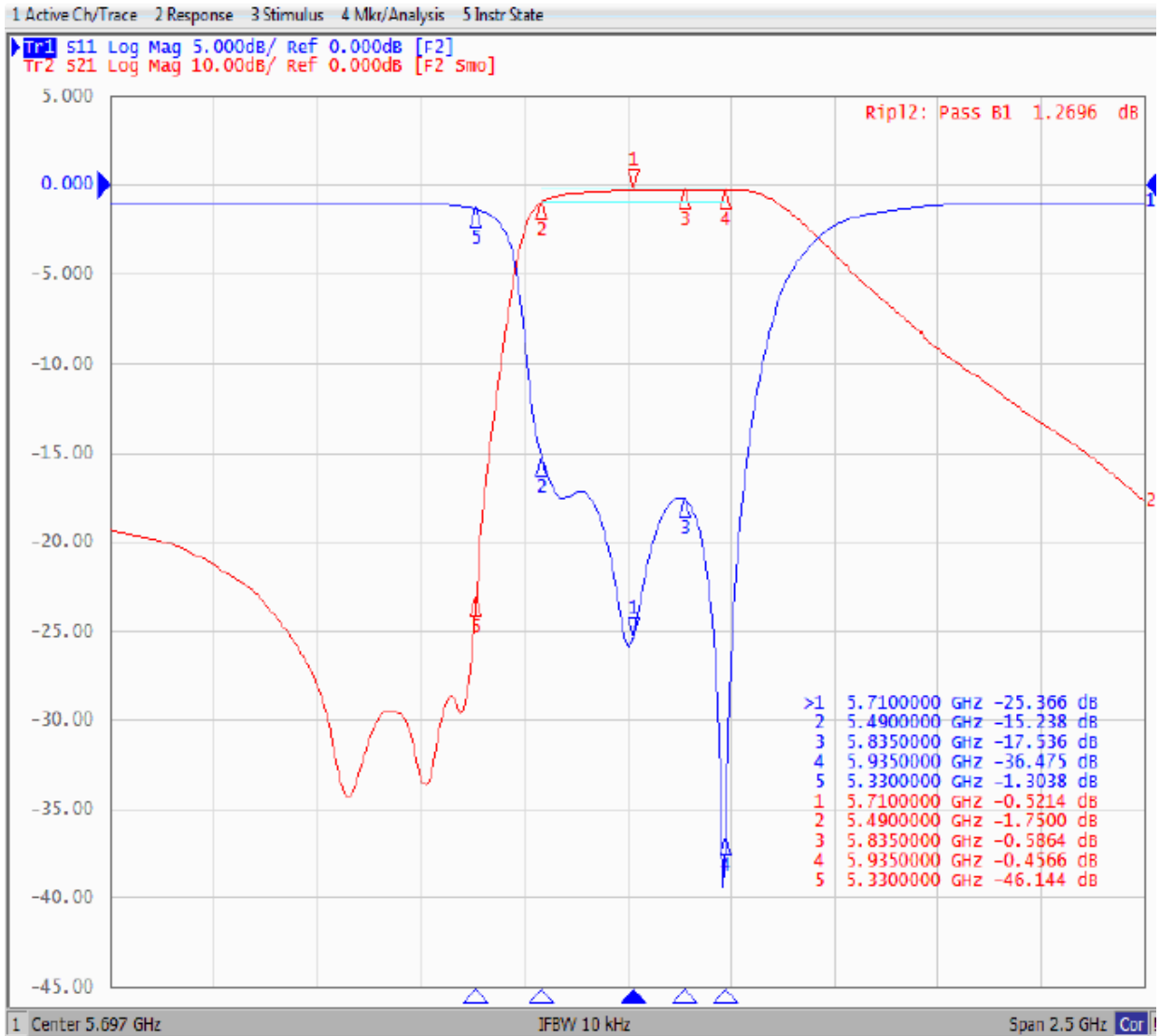


Electrostatic Sensitive Device

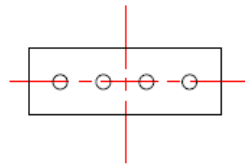
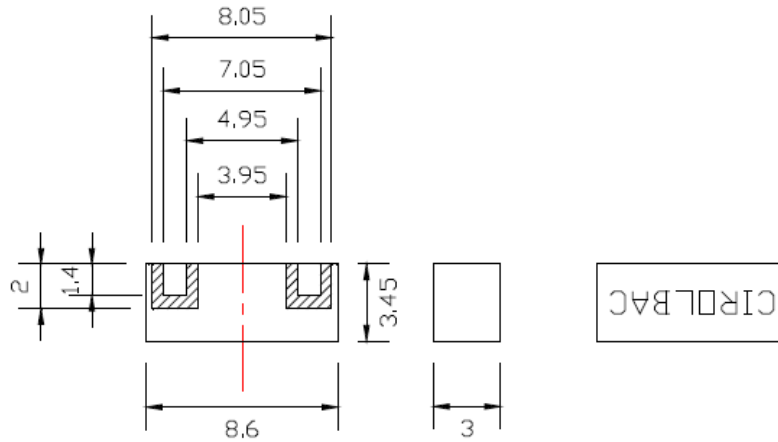
B. CHARACTERISTICS:

Item	Unit	Spec.
Center frequency, F_c	MHz	5710
Pass band Insertion Loss,	dB	2.5max
Pass band Ripple (5490~5570MHz)	dB	1.0maz
Pass band Ripple (5490~5935MHz)	dB	1.5max
Pass band Return Loss	dB	10min
Specifies the absolute value of Attenuation		
5170~5330MHz	dB	40min

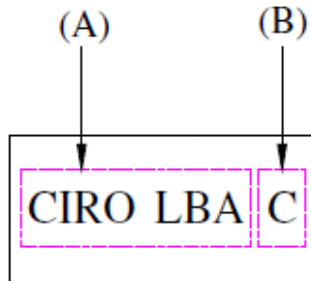
C. FREQUENCY CHARACTERISTICS:



D. OUTLINE DRAWING:



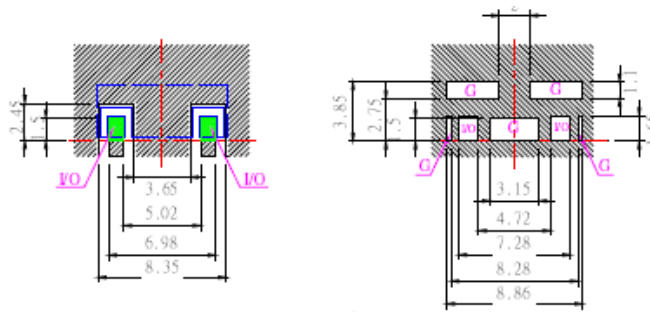
Dimensions in mm
Tolerance: ±0.25



(A) Product name : CIRO LBA
(B) Year/Month : Please refer to the Table-1

(Table-1)

Year	Month	Code	Year	Month	Code	Year	Month	Code	Year	Month	Code
2012 2016 2020 2024	1	A	2013 2017 2021 2025	1	N	2014 2018 2022 2026	1	A.	2015 2019 2023 2027	1	N.
	2	B		2	P		2	B.		2	P.
	3	C		3	Q		3	C.		3	Q.
	4	D		4	R		4	D.		4	R.
	5	E		5	S		5	E.		5	S.
	6	F		6	T		6	F.		6	T.
	7	G		7	U		7	G.		7	U.
	8	H		8	V		8	H.		8	V.
	9	J		9	W		9	J.		9	W.
	10	K		10	X		10	K.		10	X.
	11	L		11	Y		11	L.		11	Y.
	12	M		12	Z		12	M.		12	Z.



Tolerance ± 0.20
 I/O : Input/Output
 G : Ground



Electrode



Solder Resist

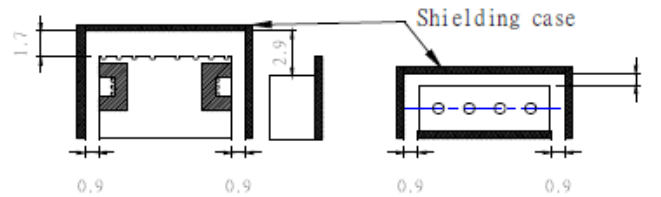


I/O Pads must be connected to lines with 50Ω impedance. In the application a termination of 50Ω must be realized.

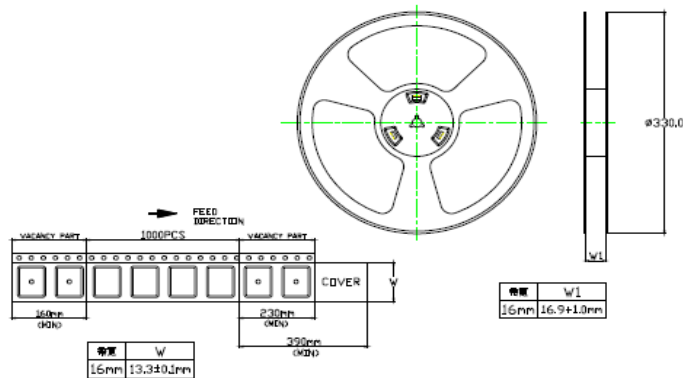
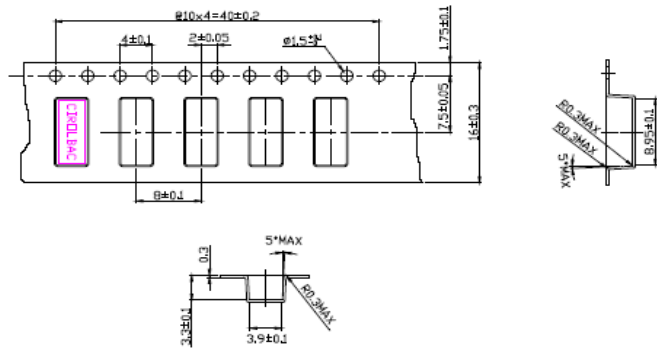


Solder LAND

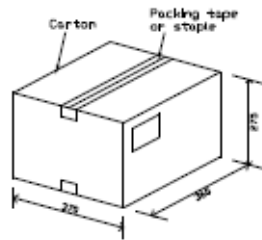
3-2-3 Shielding case layout guide (min)



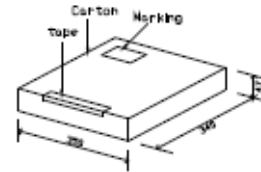
E. PACKING:



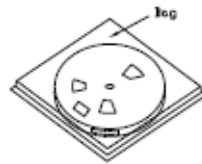
1. Outer Carton
Quantity:5000PCS



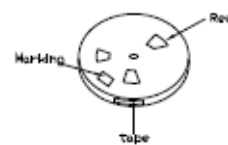
2. Inner Carton
Quantity:1000PCS



3. Bag
Quantity:1000PCS



4. Taping
Quantity:1000PCS



Unit:mm

F. RECOMMENDED REFLOW PROFILE:

Phase	Profile features	Pb-Free Assembly (SnAgCu)
PREHEAT	-Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(ts) form (Tsmin to Tsmax)	150°C 200°C 60-120 seconds
RAMP-UP	Avg. Ramp-up Rate (Tsmax to TP)	3°C/second(max)
REFLOW	-Temperature(TL) -Total Time above TL (t L)	217°C 30-100 seconds
PEAK	-Temperature(TP) -Time(tp)	260°C 3 second
RAMP-DOWN	Rate	6°C / second max.
Time from 25°C to Peak Temperature		8 minutes max.
Composition of solder paste		96.5Sn/3Ag/0.5Cu
Solder Paste Model		SHENMAO PF606-P26

The graphic shows temperature profile for component assembly process in reflow ovens

